

#5/Response
(NE)PATENT APPLICATION
Serial No. 10/043,709

3/12/03

Hays

CERTIFICATE OF FACSIMILE

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being deposited via facsimile no. (703) 872-9319 on _____.

Signed: _____

Kathy Dixon

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re : Kuo-Yu Chou, et al. : Docket No. 67,200-603

Serial No. : 10/043,709 : Art Unit No. 2814

Filing Date : January 9, 2002 : Examiner: Le, Thao X

Paper No. : 5 : Confirmation No: 6454

Invention Title: **A SINGLE LAYER WIRING BOND PAD WITH OPTIMUM
AL FILM THICKNESS IN CU/FSG PROCESS FOR DEVICES
UNDER PADS**

RESPONSE TO FINAL OFFICE ACTION

FAX RECEIVED

MAR 10 2003

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

TECHNOLOGY CENTER 2800

Sir:

In response to the Official Action dated January 29, 2003 (Paper No. 4), Applicants respectfully request reconsideration and further examination of all claims presented.